## TV-Tuner-IC with Two Separate Oscillators and Mixers, SAW-Driver and Dual-State Band Switch

## Features

- Frequency range from 48 to 860 MHz .
- Band A: balanced high impedance mixer input and amplitude controlled oscillator.
- Band C: balanced low impedance mixer input and symmetrical oscillator.
- Voltage regulator for stable operating characteristics.
- ESD protection on all pins except oscillator pins and RF-inputs.

Package: SO20

- SAW filter driver with low impedance output.


## Block Diagram



Figure 1. Block diagram pinning of U2320

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## U2320B-AFL

## Pin Configuration

| Osc A, base | 1 | 20 | GND (RF) | Pin | Symbol | Function |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  |  |  |  | 1 | Osc A, base | Oscillator band A, base |
| GND (common) | 2 | 19 | RF in, A | 2 | GND <br> (common) | Ground, common |
|  |  |  | RF in, A | 3 | Osc A, coll. | Oscillator band A, collector |
| Osc A, coll. | 3 | 18 |  | 4, 7 | Osc B, base | Oscillator band B, bases |
|  |  |  |  | 5,6 | Osc B, coll. | Oscillator band B, collectors |
| Osc B, base | 4 | 17 | RF in, B | 8 | Band sw. | Dual-state band switch |
|  |  |  |  | 9, 10 | SAWF, out | SAW filter driver outputs |
| Osc B, coll. | 5 | 16 | RF in, B | 11, 12 | SAWF, inp. | SAW filter driver input |
|  |  |  |  | 13, 14 | Mix, out | Mixer outputs, open collector |
| Osc B, coll. | 6 | 15 | $\mathrm{V}_{\mathrm{S}}$ | 15 | $\mathrm{V}_{\mathrm{S}}$ | Supply voltage $\mathrm{V}_{\text {S }}$ |
|  |  |  |  | 16, 17 | RF in, B | RF inputs, band B |
| Osc B, base | 7 | 14 | Mix, out | 18, 19 | RF in, A | RF inputs, band A |
|  |  |  |  | 20 | GND (RF) | Ground, RF part |
| Band sw. | 8 | 13 | Mix, out |  |  |  |
| SAWF, out | 9 | 12 | SAWF, inp. |  |  |  |
| SAWF, out. | 10 | 11 | SAWF, in.p. |  |  |  |

## Absolute Maximum Ratings

All voltages are referred to GND, Pin 2

| Parameters | Symbol | Min. | Typ. | Max. | Unit |
| :--- | :---: | :---: | :---: | :---: | :---: |
| Supply voltage | Pin 15 | $\mathrm{V}_{\mathrm{S}}$ |  |  | 13.5 |
| RF inputs | Pin 16-19 |  |  |  | 5.0 |
| IF outputs | Pin 13-14 |  |  |  | V |
| Dual-state switch voltage | Pin 8 | ViDSW |  |  | 13.5 |
| Junction temperature | $\mathrm{T}_{\text {jmax }}$ |  |  | V |  |
| Storage temperature | $\mathrm{T}_{\text {stor }}$ | -40 |  | 150 | V |

## Operating Range

All voltages are referred to GND, Pin 2

| Parameters | Test Conditions / Pins | Symbol | Min | Typ | Max | Unit |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
| Supply voltage | Pin 13-15 | Vs | 10.8 | 12 | 13.2 | V |
| Ambient temperature | With heat conductive glue | $\mathrm{T}_{\mathrm{amb}}$ | -25 |  | 70 | ${ }^{\circ} \mathrm{C}$ |
| Thermal resistance | Test conditions page 6 <br> SO20 Package | $\mathrm{R}_{\text {thJA }}$ |  | 90 |  | K/W |

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## Electrical Characteristics

Test conditions (unless otherwise specified): $\mathrm{V}_{\mathrm{s}}=12 \mathrm{~V}, \mathrm{~T}_{\mathrm{amb}}=25^{\circ} \mathrm{C}$. Reference point Pin 2

| Parameters | Test Conditions / Pins | Symbol | Min | Typ | Max | Unit |
| :--- | :---: | :---: | :---: | :---: | :---: | :---: |
| Supply voltage | Pin 13-15 | Vs | 10.8 | 12.0 | 13.2 | V |
| Supply current | $13-15$ | Pin | Is |  | 42 | 50 |

## SAW filter driver $\mathbf{f i}=\mathbf{3 6} \mathbf{~ M H z}$

| Input impedance | 12 | Pin 11, | ZiSAW |  | 450 |  |
| :--- | ---: | :--- | :--- | :--- | :--- | :---: |
| Output impedance | Pin 9,10 | ZoSAW |  | 70 |  | $\Omega$ |
| Voltage gain | Pin $11,12,9,10$ | GvSAW |  | 19 |  | dB |

Band A (note 1)

| Input frequency range | Pin 18 | fiA | 48 |  | 470 | MHz |
| :--- | :--- | :---: | :---: | :---: | :---: | :---: |
| Input impedance | Figure 3 Pin 18 | S11A |  |  |  |  |
| Gain (note 4) | Pin I/P to O/P | GA |  | 30 |  | dB |
| Noise figure DSB (note 2) | fiA $=50 \mathrm{MHz}$ <br> Pin I/P to O/P <br> fiA $=150 \mathrm{MHz}$ | NF |  | 11.5 <br> 12 |  | dB <br> dB |
| Input level for (note 3): | Each carrier |  |  |  |  |  |
| IM3 (interm. of 3rd order) | fiA $=71 \mathrm{MHz} \quad$ Pin I/P | ViA |  | -22 |  | dBm |
| IM2 (interm. of 2nd order) | fiA $=71 \mathrm{MHz} \quad$ Pin I/P | ViA |  | -22 |  | dBm |


| Band B (note 1) |  |  |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Input frequency range | Pin 16, 17 | fiB | 470 |  | 860 | MHz |
| Input impedance | Figure $3 \quad$ Pin 16, 17 | S11B |  |  |  |  |
| Gain (note 4) | Pin I/P to O/P | GB |  | 34 |  | dB |
| Noise figure DSB (note 2) | $\mathrm{fiB}=500 \mathrm{MHz}$ Pin I/P to O/P $\mathrm{fiB}=800 \mathrm{Mhz}$ | NF |  | $\begin{aligned} & 10.5 \\ & 11.5 \end{aligned}$ |  | $\begin{aligned} & \mathrm{dB} \\ & \mathrm{~dB} \end{aligned}$ |
| Input level for (note 3) | Each carrier |  |  |  |  |  |
| IM3 (interm. of 3rd order) | $\mathrm{fiB}=600 \mathrm{MHz} \quad$ Pin I/P | ViB |  | -27 |  | dBm |

Notes:

1) The RF input B is symmetrical driven by means of a hybrid for $180^{\circ}$ phase shifting, consequently the source impedance is $100 \Omega$. All other impedance for RF tests is $50 \Omega$.
2) The noise figure (NF) is the value for double-side-band measurement.
3) The intermodulation test (2-carrier-method) which is made on IF-centre is in reference to a signal-to-IM ratio of 60 dB .
4) Gain is the ratio of the voltage at the primary coil of the available voltage at the input.

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Test and Principle Application Circuit


Figure 2. Test and principle application circuit

## PCB for the $\mathbf{R}_{\text {thJA }}-$ Measurement



Figure 3. PCB for the $\mathrm{R}_{\text {thJA }}$-measurement

## Input Impedance Mixer Band A (S11A) and B (S11B)



Figure 4. Input impedance mixer band $\mathrm{A}(\mathrm{S} 11 \mathrm{~A})$ and B (S11B)

## 1 VHF-Low

Normalised to $50 \Omega$, measuring range 45 MHz to 750 MHz .

## 2 VHF-High and UHF

Normalised to $50 \Omega$, measuring range 45 MHz to 1045 MHz . Input is driven symmetrical.
The output impedance of the hybrid is $100 \Omega$, the measured level is then calculated in reference to $50 \Omega$.

## Dimensions in mm:

Package: SO20

technical drawings according to DIN specifications

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2. Regularly and continuously improve the performance of our products, processes, distribution and operating systems with respect to their impact on the health and safety of our employees and the public, as well as their impact on the environment.

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3. Council Decision 88/540/EEC and 91/690/EEC Annex A, B and C (transitional substances) respectively.

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